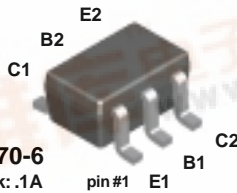




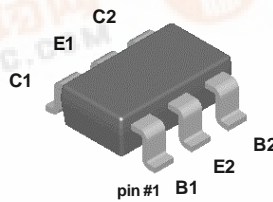
## FFB3904



SC70-6  
Mark: .1A

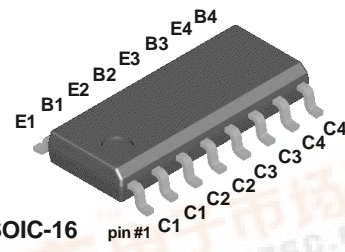
NOTE: The pinouts are symmetrical; pin 1 and pin 4 are interchangeable. Units inside the carrier can be of either orientation and will not affect the functionality of the device.

## FMB3904



SuperSOT™-6  
Mark: .1A  
Dot denotes pin #1

## MMPQ3904



SOIC-16  
Mark: MMPQ3904

## NPN Multi-Chip General Purpose Amplifier

This device is designed as a general purpose amplifier and switch. The useful dynamic range extends to 100 mA as a switch and to 100 MHz as an amplifier. Sourced from Process 23.

### Absolute Maximum Ratings\*

T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	40	V
V <sub>CBO</sub>	Collector-Base Voltage	60	V
V <sub>EBO</sub>	Emitter-Base Voltage	6.0	V
I <sub>C</sub>	Collector Current - Continuous	200	mA
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.
- 3) All voltages (V) and currents (A) are negative polarity for PNP transistors.

### Thermal Characteristics

T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Characteristic	Max			Units
		FFB3904	FMB3904	MMPQ3904	
P <sub>D</sub>	Total Device Dissipation	300	700	1,000	mW
	Derate above 25°C	2.4	5.6	8.0	mW/°C
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient	415	180		°C/W
	Effective 4 Die			125	°C/W
	Each Die			240	°C/W



## NPN Multi-Chip General Purpose Amplifier

(continued)

### Electrical Characteristics

$T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS</b>						
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage	$I_C = 1.0\text{ mA}, I_B = 0$	40			V
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage	$I_C = 10\ \mu\text{A}, I_E = 0$	60			V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage	$I_E = 10\ \mu\text{A}, I_C = 0$	6.0			V
$I_{BL}$	Base Cutoff Current	$V_{CE} = 30\text{ V}, V_{EB} = 0$			50	nA
$I_{CEX}$	Collector Cutoff Current	$V_{CE} = 30\text{ V}, V_{EB} = 0$			50	nA

### ON CHARACTERISTICS\*

$h_{FE}$	DC Current Gain	$I_C = 0.1\text{ mA}, V_{CE} = 1.0\text{ V}$ <b>MMPQ3904</b> $I_C = 1.0\text{ mA}, V_{CE} = 1.0\text{ V}$ <b>MMPQ3904</b> $I_C = 10\text{ mA}, V_{CE} = 1.0\text{ V}$ <b>MMPQ3904</b> $I_C = 50\text{ mA}, V_{CE} = 1.0\text{ V}$ $I_C = 100\text{ mA}, V_{CE} = 1.0\text{ V}$	40 30 70 50 100 75 60 30		300	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 10\text{ mA}, I_B = 1.0\text{ mA}$ $I_C = 50\text{ mA}, I_B = 5.0\text{ mA}$			0.2 0.3	V V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C = 10\text{ mA}, I_B = 1.0\text{ mA}$ $I_C = 50\text{ mA}, I_B = 5.0\text{ mA}$	0.65		0.85 0.95	V V

### SMALL SIGNAL CHARACTERISTICS (MMPQ3904 only)

$f_T$	Current Gain - Bandwidth Product	$I_C = 10\text{ mA}, V_{CE} = 20\text{ V},$ $f = 100\text{ MHz}$		250		MHz
$C_{obo}$	Output Capacitance	$V_{CB} = 5.0\text{ V}, I_E = 0,$ $f = 140\text{ kHz}$		4.0		pF
$C_{ibo}$	Input Capacitance	$V_{EB} = 0.5\text{ V}, I_C = 0,$ $f = 140\text{ kHz}$		8.0		pF

\* Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$

**NOTE:** All voltages (V) and currents (A) are negative polarity for PNP transistors.

FFB3904 / FMB3904 / MMPQ3904

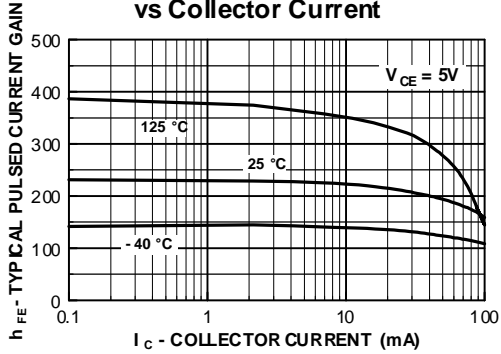
# NPN Multi-Chip General Purpose Amplifier

(continued)

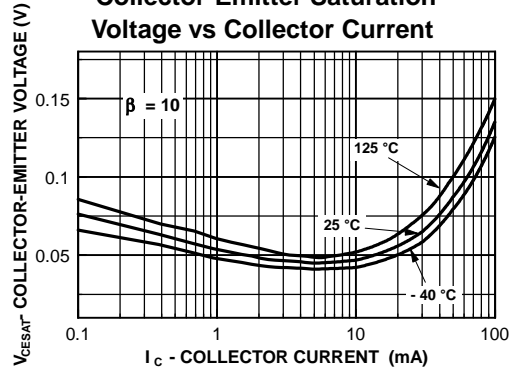
FFB3904 / FMB3904 / MMPQ3904

## Typical Characteristics

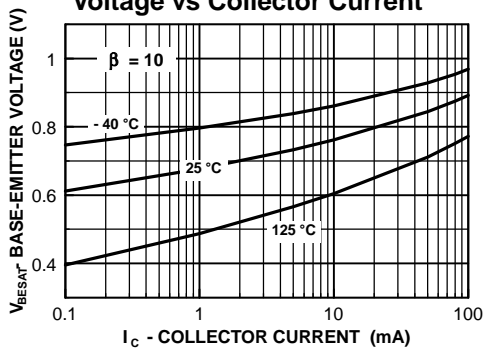
**Typical Pulsed Current Gain vs Collector Current**



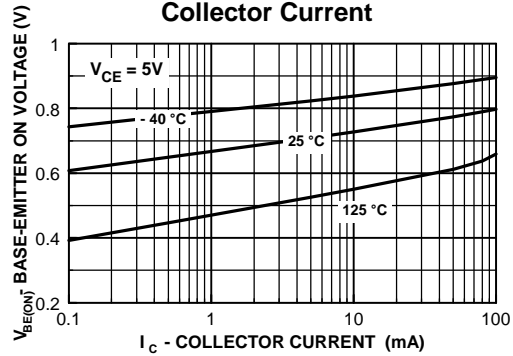
**Collector-Emitter Saturation Voltage vs Collector Current**



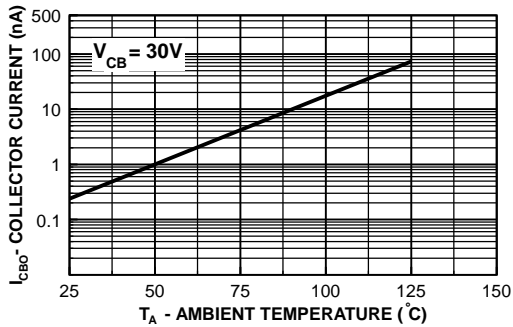
**Base-Emitter Saturation Voltage vs Collector Current**



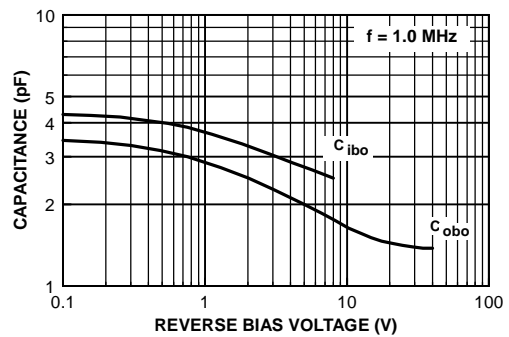
**Base-Emitter ON Voltage vs Collector Current**



**Collector-Cutoff Current vs Ambient Temperature**



**Capacitance vs Reverse Bias Voltage**



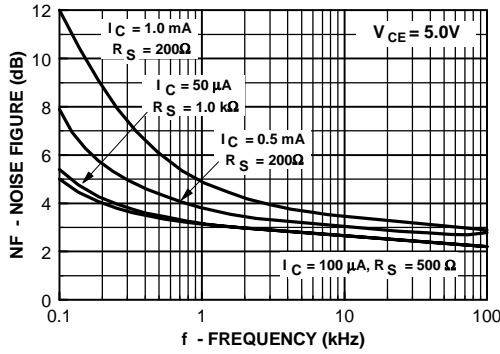
# NPN Multi-Chip General Purpose Amplifier

(continued)

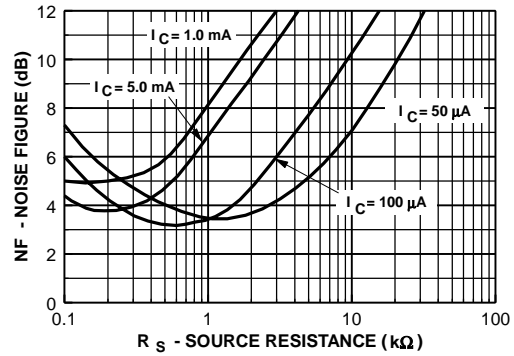
FFB3904 / FMB3904 / MMPQ3904

## Typical Characteristics (continued)

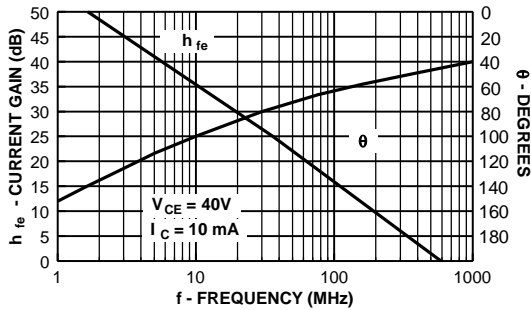
### Noise Figure vs Frequency



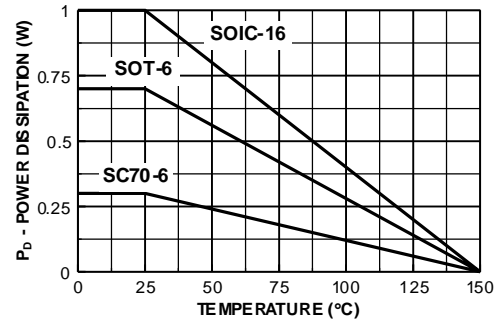
### Noise Figure vs Source Resistance



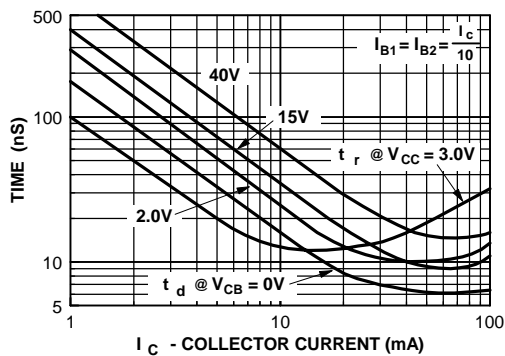
### Current Gain and Phase Angle vs Frequency



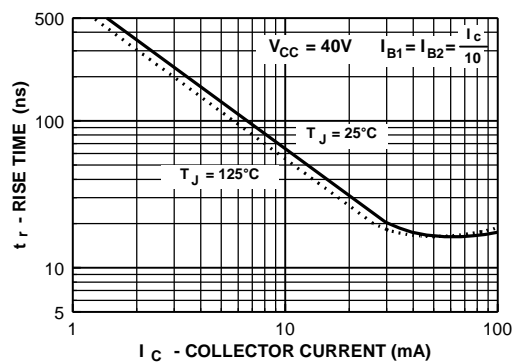
### Power Dissipation vs Ambient Temperature



### Turn-On Time vs Collector Current



### Rise Time vs Collector Current



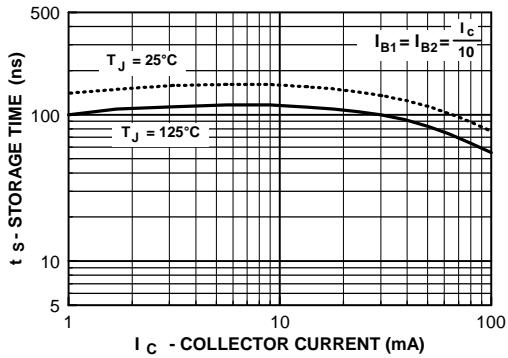
# NPN Multi-Chip General Purpose Amplifier

(continued)

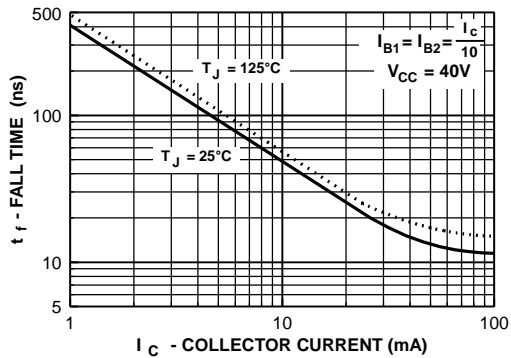
FFB3904 / FMB3904 / MMPQ3904

## Typical Characteristics (continued)

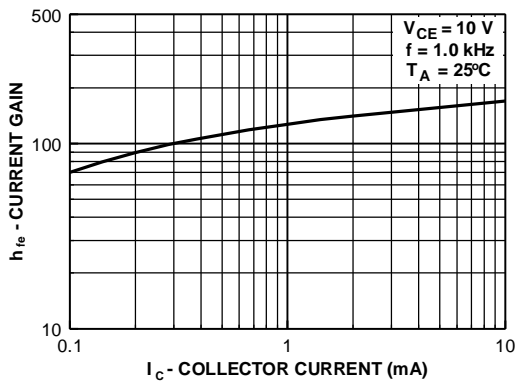
### Storage Time vs Collector Current



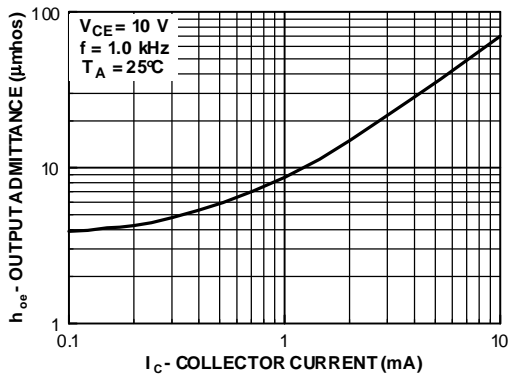
### Fall Time vs Collector Current



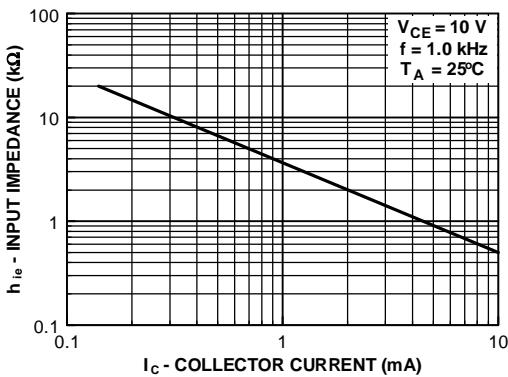
### Current Gain



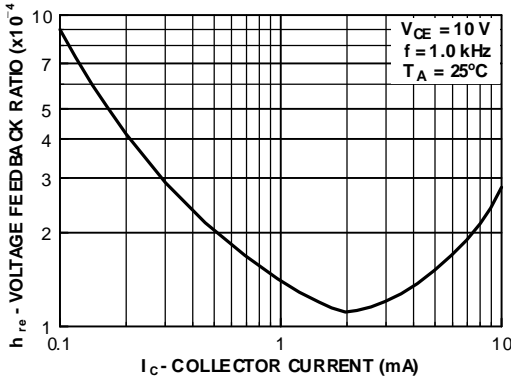
### Output Admittance



### Input Impedance



### Voltage Feedback Ratio



# NPN Multi-Chip General Purpose Amplifier

(continued)

FFB3904 / FMB3904 / NMPQ3904

## Test Circuits

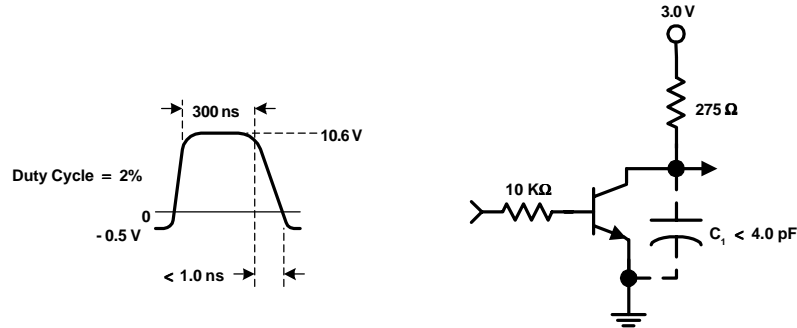


FIGURE 1: Delay and Rise Time Equivalent Test Circuit

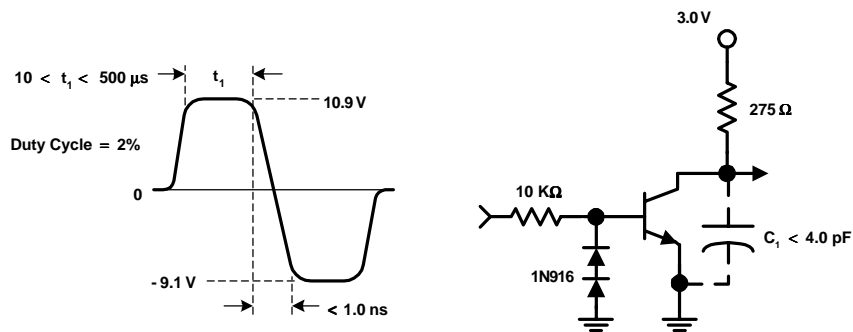


FIGURE 2: Storage and Fall Time Equivalent Test Circuit

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DOME™	ISOPLANAR™	Quiet Series™	
E <sup>2</sup> CMOS™	MICROWIRE™	SILENT SWITCHER®	
EnSigna™	OPTOLOGIC™	SMART START™	
FACT™	OPTOPLANAR™	SuperSOT™-3	
FACT Quiet Series™	PACMAN™	SuperSOT™-6	
FAST®	POP™	SuperSOT™-8	

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